Surface Mount Ultrafast Power Rectifiers

This series employs the state-of-the-art epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for high voltage, high frequency rectification, or as free wheeling and protection diodes, in surface mount applications where compact size and weight are critical to the system.

Features

- Small Compact Surface Mountable Package with J-Bend Leads
- Rectangular Package for Automated Handling
- High Temperature Glass Passivated Junction
- Low Forward Voltage Drop (0.71 to 1.05 Volts Max @ 3.0 A, T_J = 150°C)
- SURS8 Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable*
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

Mechanical Characteristics

- Case: Epoxy, Molded
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight: 217 mg (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Shipped in 16 mm Tape and Reel, 2500 units per reel
- Polarity: Polarity Band on Plastic Body Indicates Cathode Lead
- Device Meets MSL1 Requirements
- ESD Ratings:
 - Machine Model, C (> 400 V)
 - Human Body Model, 3B (> 8 kV)



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ULTRAFAST RECTIFIERS 3.0 AMPERES 200–600 VOLTS



SMC 2-LEAD CASE 403AC

MARKING DIAGRAM



U3 = Specific Device Code

х

- = J (360T3)
- A = Assembly Location**
- Y = Year
- WW = Work Week
- **The Assembly Location code (A) is front side optional. In cases where the Assembly Location is stamped in the package, the front side assembly code may be blank.

ORDERING INFORMATION

Device	Package	Shipping [†]
MURS320T3G	SMC (Pb-Free)	2,500 / Tape & Reel
MURS340T3G	SMC (Pb-Free)	2,500 / Tape & Reel
MURS360T3G	SMC (Pb-Free)	2,500 / Tape & Reel
SURS8340T3G*	SMC (Pb-Free)	2,500 / Tape & Reel
SURS8320T3G*	SMC (Pb-Free)	2,500 / Tape & Reel
SURS8360T3G*	SMC (Pb-Free)	2,500 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MAXIMUM RATINGS

Rating	Symbol	MURS320T3G/ SURS8320T3G	MURS340T3G/ SURS8340T3G	MURS360T3G/ SURS8360T3G	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	200	400	600	V
Average Rectified Forward Current	I _{F(AV)}	3.0 @ T _L = 140°C 4.0 @ T _L = 130°C	3.0 @ T _L = 130°C 4.0 @ T _L = 115°C	3.0 @ T _L = 130°C 4.0 @ T _L = 115°C	А
Non-Repetitive Peak Surge Current (Surge applied at rated load conditions halfwave, single phase, 60 Hz)	I _{FSM}	100		A	
Operating Junction Temperature	TJ	- 65 to +175			°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

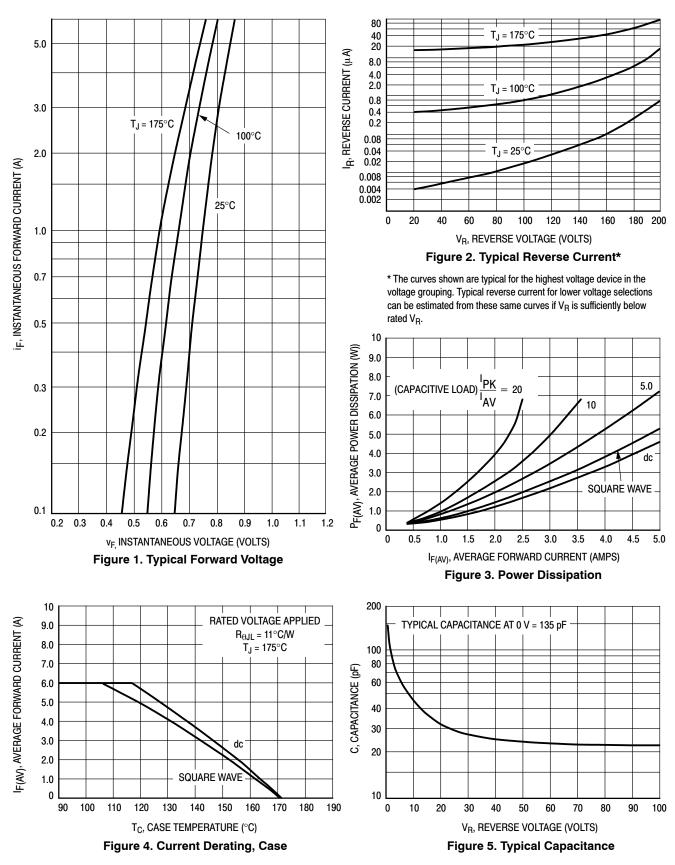
Thermal Resistance, Junction-to-Lead $$R_{\theta J}$$	11	°C/W
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ELECTRICAL CHARACTERISTICS

$\begin{array}{l} \mbox{Maximum Instantaneous Forward Voltage (Note 1)} \\ (i_F = 3.0 \mbox{ A}, \mbox{ T}_J = 25^\circ \mbox{C}) \\ (i_F = 4.0 \mbox{ A}, \mbox{ T}_J = 25^\circ \mbox{C}) \\ (i_F = 3.0 \mbox{ A}, \mbox{ T}_J = 150^\circ \mbox{C}) \end{array}$	v _F	0.875 0.89 0.71	1.25 1.28 1.05	1.25 1.28 1.05	V
Maximum Instantaneous Reverse Current (Note 1) (Rated dc Voltage, $T_J = 25^{\circ}C$) (Rated dc Voltage, $T_J = 150^{\circ}C$)	i _R	5.0 150	10 250	10 250	μΑ
$\begin{array}{l} \mbox{Maximum Reverse Recovery Time} \\ (i_F = 1.0 \mbox{ A, di/dt} = 50 \mbox{ A/}\mu s) \\ (i_F = 0.5 \mbox{ A, } i_R = 1.0 \mbox{ A, } I_{REC} \mbox{ to } 0.25 \mbox{ A}) \end{array}$	t _{rr}	35 25	75 50	75 50	ns
Maximum Forward Recovery Time (i _F = 1.0 A, di/dt = 100 A/µs, Recovery to 1.0 V)	t _{fr}	25	50	50	ns
Typical Peak Reverse Recovery Current (I _F = 1.0 A, di/dt = 50 A/µs)	I _{RM}	0.8			A

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

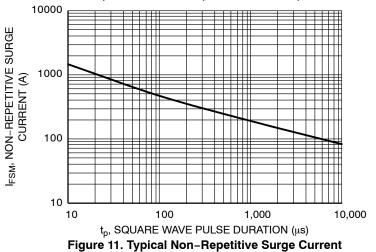
1. Pulse Test: Pulse Width = 300 μ s, Duty Cycle \leq 2.0%.



MURS320T3G/SURS8320T3G

400 200 5.0 T_J = 175°C 80 IR, REVERSE CURRENT (MA) 40 20 8.0 3.0 $T_J = 175^{\circ}C$ 100°C 4.0 2.0 $T_J = 100^{\circ}C$ 2.0 0.8 0.4 0.2 25°C 0.08 ТJ = 25°C i_F, INSTANTANEOUS FORWARD CURRENT (A) 1.0 0.04 0.02 0.008 0.004 0.7 0 100 200 300 400 500 600 700 0.5 V_R, REVERSE VOLTAGE (V) Figure 7. Typical Reverse Current* * The curves shown are typical for the highest voltage device in the 0.3 voltage grouping. Typical reverse current for lower voltage selections can be estimated from these same curves if V_R is sufficiently below 0.2 rated V_R. PF(AV), AVERAGE POWER DISSIPATION (WATTS) 10 9.0 0.1 8.0 7.0 0.07 SQUARE WAVE 6.0 dc (CAPACITIVE LOADS) 0.05 5.0 4.0 PΚ 20 10 5.0 3.0 AV 0.03 2.0 0.02 1.0 0.3 0.5 0.7 0.9 1.1 1.3 1.5 1.7 1.9 2.1 2.3 0 0.5 1.0 1.5 2.5 3.0 v_E INSTANTANEOUS VOLTAGE (VOLTS) 0 2.0 3.5 4.0 4.5 5.0 IF(AV), AVERAGE FORWARD CURRENT (A) Figure 6. Typical Forward Voltage Figure 8. Power Dissipation 10 100 I_{F(AV)}, AVERAGE FORWARD CURRENT (A) 9.0 90 8.0 80 TYPICAL CAPACITANCE AT 0 V = 75 pF 7.0 C, CAPACITANCE (pF) 70 60 6.0 5.0 50 4.0 40 dc 3.0 30 SQUARE WAVE 2.0 20 1.0 10 0 0 70 80 90 100 110 120 130 140 150 160 170 10 20 30 40 50 60 70 80 0 90 100 T_C, CASE TEMPERATURE (°C) V_R, REVERSE VOLTAGE (V) Figure 9. Current Derating, Case Figure 10. Typical Capacitance

TYPICAL CHARACTERISTICS

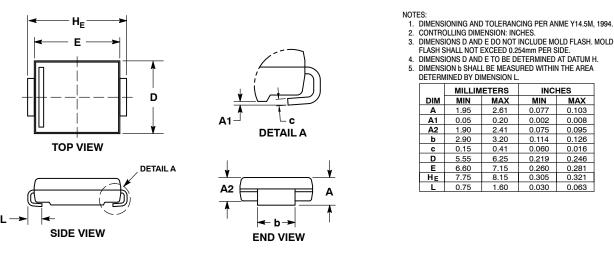


MURS340T3G, SURS8340T3G, MURS360T3G, SURS8360T3G

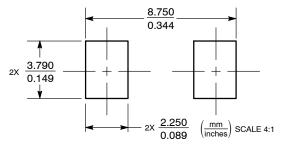
*Typical performance based on a limited sample size. ON Semiconductor does not guarantee ratings not listed in the Maximum Ratings table.

PACKAGE DIMENSIONS

SMC 2-LEAD CASE 403AC ISSUE A



RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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